

WHAT IS CLAIMED IS:

1. A copper alloy suitable for an IC lead pin for a  
pin grid array provided on a plastic substrate, which  
5 copper alloy is selected from the group consisting of:

a copper alloy containing 0.05 to 0.5 wt% of Zn and  
0.05 to 0.5 wt% of Mg, with the balance being made of  
unavoidable impurities and Cu;

10 a copper alloy containing 0.1 to 1.0 wt% of Sn, with  
the balance being made of unavoidable impurities and Cu;

a copper alloy containing 0.1 to 1.0 wt% of Sn and  
0.1 to 0.6 wt% of Ag, with the balance being made of  
unavoidable impurities and Cu;

15 a copper alloy containing 2.1 to 2.6 wt% of Fe, 0.05  
to 0.2 wt% of Zn, and 0.015 to 0.15 wt% of P, with the  
balance being made of unavoidable impurities and Cu; and

a copper alloy containing 0.4 to 1.1 wt% of Cr, with  
the balance being made of unavoidable impurities and Cu,

20 wherein the copper alloy has conductivity of 50%  
IACS or more, and tensile stress of 400 MPa or more but  
650 MPa or less.

2. The copper alloy as claimed in claim 1, which is  
the copper alloy containing 0.05 to 0.5 wt% of Zn and 0.05  
25 to 0.5 wt% of Mg, with the balance being made of

unavoidable impurities and Cu.

3. The copper alloy as claimed in claim 1, which is the copper alloy containing 0.1 to 1.0 wt% of Sn, with the  
5 balance being made of unavoidable impurities and Cu.

4. The copper alloy as claimed in claim 1, which is the copper alloy containing 0.1 to 1.0 wt% of Sn and 0.1 to 0.6 wt% of Ag, with the balance being made of  
10 unavoidable impurities and Cu.

5. The copper alloy as claimed in claim 1, which is the copper alloy containing 2.1 to 2.6 wt% of Fe, 0.05 to 0.2 wt% of Zn, and 0.015 to 0.15 wt% of P, with the  
15 balance being made of unavoidable impurities and Cu.

6. The copper alloy as claimed in claim 1, which is the copper alloy containing 0.4 to 1.1 wt% of Cr, with the balance being made of unavoidable impurities and Cu.

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